# First Call for Papers





# 18th MICROOPTICS CONFERENCE

held as ICO Topical Meeting

http://www.comemoc.com/moc13/

Sponsored by The Japan Society of Applied Physics Organized by Microoptics Group, Optical Society of Japan, JSAP



#### Co-sponsored by

- International Commission for Optics
- Tokyo Institute of Technology
- Technically co-sponsored by
- IEEE Photonics Society

#### In cooperation with

- Optical Society of America
- IEICE Electronics Society
- The Chemical Society of Japan
- · The Society of Polymer Science, Japan
- The Laser Society of Japan
- OITDA
- Japan Optomechatronics Association
- · JSPS / The 125th Committee
- JSPS / The 130th Committee (Some sponsors and cooperators are under negotiation.)

## Oct. 27 (Sun.) - Oct. 30 (Wed.), 2013 TOKYO INSTITUTE OF TECHNOLOGY Tokyo, Japan

# Paper Deadline: June 3 (Mon.), 2013

# OBJECTIVE

The 18th MICROOPTICS CONFERENCE (MOC '13) will be held at TOKYO INSTITUTE OF TECHNOLOGY, Tokyo, Japan on October 27 - October 30, 2013. This conference is sponsored by the Japan Society of Applied Physics (JSAP) and organized by Microoptics Group, the Optical Society of Japan (OSJ), JSAP and in cooperation with several academic societies and associations. The MOC'13 will be held as an ICO Topical Meeting.

The MOC '13 is intended to provide a central forum for an update and review of scientific and technical information covering a wide range of microoptics field from fundamental researches to systems and applications.

## CATEGORY

The category of the conference covers the following subjects of microoptics;

## 1. Theory, Modeling and Design

Aberrations, Dispersion, Beam optics, Guided-wave optics, Gradient-index optics, Diffractive optics, Photonic band, Slow light, Near-field optics, Nonlinear optics, Thermooptics, Plasmonics, Simulation and System design, etc.

## 2. Materials and Fabrication

Semiconductors, Crystals, Dielectric materials, Polymers, Liquid crystals, Nonlinear materials, Composite materials, Nano-materials, Metals, Spin-materials, etc.

Diffusion and Ion exchange, Lithography and Etching, Thin film deposition, Micro- and Nano-fabrication, Nano-imprint, Laser fabrication, etc.

## 3. Measurements

Spectroscopy, Interferometry, Reflectometry, Femto - second measurement, 3D measurement, Quantum measurement, etc.

## 4. Passive Devices

Fibers, Waveguides, Multi/Demultiplexers, Add-drop multiplexers, Branching and mixing components, Photonic crystals, Filters, Microlenses, Diffractive optical elements, Isolators, Polarizers, etc.

## 5. Dynamic and Functional Devices

MEMS, Switches, Modulators, Tunable devices, Wavelength converters, Nonlinear optical devices, Deflectors, Optical buffers, etc.

## 6. Active Devices

Lasers, LEDs, VCSELs, Array lasers, Amplifiers, Terahertz devices, Sensors, etc.

## 7. Integration and Packaging

Monolithic and Hybrid integration, Mounting and packaging, Micro-assembly, Si photonics, 3D integration, etc.

## 8. Conception for Applications

High power, High speed, High efficiency, High field, High Density, High sensitivity, etc.

# APPLICATION FIELD

The 18th MICROOPTICS CONFERENCE covers microoptics technologies in the following major topical fields;

## A. Optical Communications

Photonic networks, Optical cross connects, LAN, VSR, SAN, FTTH, etc.

#### **B. Optical Interconnects**

Chip/Board/System, Data transfer, etc.

#### **C.** Optical Storages

Optical heads, Disks, Near-field recording, Holographic recording, Multi-layer recording, Super resolution, etc.

## D. Equipment

Printers, Image sensors, Digital cameras, Advanced microscopes, etc.

## E. Optical Sensing and Processing

Optics for image recognition, Physical measurements, Sensors and sensing systems, Security systems, Optical computing, Bio- and Medical sensing, etc.

#### F. Displays and Lighting

LCD, PDP, FED, EL, Micromirror, Laser/LED displays, 3D displays, Solid state lighting, Illuminations, etc.

#### G. New Applications

Green Photonics, Environmental and Energy optics, Bioand Medical optics, Nano-photonics, Quantum systems, Next generation and Intelligent microoptics, Agricultural and Fishery optics, etc.

## SUBMISSION OF PAPERS

Original papers that have not been previously presented and that describe new technical contributions to the areas covered by the technical descriptions in the aforementioned category will be accepted for presentation. A detailed instruction will be available from the following Web site.

#### http://www.comemoc.com/moc13/

Papers should be submitted electronically no later than **June 3 (Mon.)**, 2013. Authors will be requested to submit 2-page paper written in English, including text, figures, tables, and references within a frame of 17 cm x 24 cm. The paper template will be available through the Web site.

## POSTER SESSION

In addition to regular oral presentation sessions, poster presentation session will be planned to stimulate detailed explanation and discussion. The author(s) of papers will be informed of the size of bulletin board for displaying summary, figures, tables, etc., when selected as poster papers.

## POST DEADLINE PAPERS

A limited number of post deadline papers will be accepted for presentation at post deadline sessions. Latest significant results obtained after the regular deadline are most welcome.

# PAPER AWARDS

Some excellent contributed papers will be awarded Best Paper Award. Moreover, some excellent papers presented by students will be awarded Student Paper Award.

## FINANCIAL SUPPORT FOR OVERSEAS STUDENTS

Limited financial support is considered for presentation by students from overseas. Details will be announced in the Final Call for Papers.

## **OFFICIAL LANGUAGE**

The official language of MOC '13 is English.

## **CONFERENCE VENUE**

The MOC'13 will take place at Ookayama campus of Tokyo Institute of Technology, which is the largest national university of science and technology in Japan founded in 1881. The campus is located close to the downtown Tokyo. All sessions will be held at TOKYO TECH FRONT, which is an alumni-club building just in front of Ookayama Station.



Tokyo Tech Front, Tokyo Institute of Technology Ookayama 2-12-12, Meguro-ku, Tokyo, Japan TEL/FAX:+81-3-5734-3737 http://www.titech.ac.jp/english/ http://www.somuka.titech.ac.jp/ttf/index.html (Japanese only)

# ACCESS MAP

#### From Narita Airport

- 1. Take Skyliner to Nippori or Narita Express to Shinagawa.
- 2. Change to JR Yamanote Line (Outer Loop).
- Get off at Meguro and transfer to Tokyu Meguro Line to Ookayama.

#### From Haneda Airport

- Take Tokyo Monorail to Hamamatsucho or Keikyu Line to Shinagawa.
- 2. Change to JR Yamanote Line (Outer Loop).
- Get off at Meguro and transfer to Tokyu Meguro Line to Ookayama.



# FREE CIRCULATION OF SCIENTISTS

To secure IUPAP sponsorship, the organizers have provided assurance that MOC'13 will be conducted in accordance with IUPAP principles as stated in the ICSU-Document "Universality of Science" (sixth edition, 1989) regarding the free circulation of scientists for international purposes. In particular, no bona fide scientist will be excluded from participation on the grounds of national origin, nationality, or political considerations unrelated to science.

\*IUPAP sponsorship is applied for ICO Topical Meetings.

## FURTHER INFORMATION

The Final Call for Papers will be issued in March 2013. The latest information on the conference will be also presented on the Web site.

#### http://www.comemoc.com/moc13/

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(Some members are under negotiation.)